

## OptiMOS™3 Power-Transistor

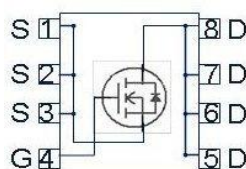
### Features

- Ideal for high frequency switching and sync. rec.
- Optimized technology for DC/DC converters
- Excellent gate charge x  $R_{DS(on)}$  product (FOM)
- Very low on-resistance  $R_{DS(on)}$
- Superior thermal resistance
- N-channel, logic level
- 100% avalanche tested
- Pb-free plating; RoHS compliant
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Halogen-free according to IEC61249-2-21

|         |                                                                                    |
|---------|------------------------------------------------------------------------------------|
| Type    | BSC067N06LS3 G                                                                     |
|         |  |
| Package | PG-TDSON-8                                                                         |
| Marking | 067N06LS                                                                           |

### Product Summary

|                  |     |    |
|------------------|-----|----|
| $V_{DS}$         | 60  | V  |
| $R_{DS(on),max}$ | 6.7 | mΩ |
| $I_D$            | 50  | A  |



**Maximum ratings**, at  $T_i=25\text{ °C}$ , unless otherwise specified

| Parameter                                    | Symbol        | Conditions                                                                | Value | Unit |
|----------------------------------------------|---------------|---------------------------------------------------------------------------|-------|------|
| Continuous drain current                     | $I_D$         | $V_{GS}=10\text{ V}$ , $T_C=25\text{ °C}$                                 | 50    | A    |
|                                              |               | $V_{GS}=10\text{ V}$ , $T_C=100\text{ °C}$                                | 50    |      |
|                                              |               | $V_{GS}=4.5\text{ V}$ , $T_C=25\text{ °C}$                                | 50    |      |
|                                              |               | $V_{GS}=4.5\text{ V}$ , $T_C=100\text{ °C}$                               | 37    |      |
|                                              |               | $V_{GS}=10\text{ V}$ , $T_A=25\text{ °C}$ , $R_{thJA}=50\text{ K/W}^{2)}$ | 15    |      |
| Pulsed drain current <sup>3)</sup>           | $I_{D,pulse}$ | $T_C=25\text{ °C}$                                                        | 200   |      |
| Avalanche energy, single pulse <sup>4)</sup> | $E_{AS}$      | $I_D=50\text{ A}$ , $R_{GS}=25\text{ Ω}$                                  | 47    | mJ   |
| Gate source voltage                          | $V_{GS}$      |                                                                           | ±20   | V    |

<sup>1)</sup> J-STD20 and JESD22

<sup>2)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

<sup>3)</sup> See figure 3 for more detailed information

<sup>4)</sup> See figure 13 for more detailed information

Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified

| Parameter                           | Symbol                | Conditions                                                    | Value       | Unit |
|-------------------------------------|-----------------------|---------------------------------------------------------------|-------------|------|
| Power dissipation                   | $P_{\text{tot}}$      | $T_C=25\text{ °C}$                                            | 69          | W    |
|                                     |                       | $T_A=25\text{ °C}$ ,<br>$R_{\text{thJA}}=50\text{ K/W}^{(2)}$ | 2.5         |      |
| Operating and storage temperature   | $T_j, T_{\text{stg}}$ |                                                               | -55 ... 150 | °C   |
| IEC climatic category; DIN IEC 68-1 |                       |                                                               | 55/150/56   |      |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

#### Thermal characteristics

|                                     |                   |                                               |   |   |     |     |
|-------------------------------------|-------------------|-----------------------------------------------|---|---|-----|-----|
| Thermal resistance, junction - case | $R_{\text{thJC}}$ |                                               | - | - | 1.8 | K/W |
| Device on PCB                       | $R_{\text{thJA}}$ | minimal footprint                             | - | - | 62  |     |
|                                     |                   | 6 cm <sup>2</sup> cooling area <sup>(2)</sup> | - | - | 50  |     |

Electrical characteristics, at  $T_j=25\text{ °C}$ , unless otherwise specified

#### Static characteristics

|                                  |                             |                                                                                       |     |     |      |               |
|----------------------------------|-----------------------------|---------------------------------------------------------------------------------------|-----|-----|------|---------------|
| Drain-source breakdown voltage   | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}}=0\text{ V}$ , $I_{\text{D}}=1\text{ mA}$                               | 60  | -   | -    | V             |
| Gate threshold voltage           | $V_{\text{GS(th)}}$         | $V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=35\text{ }\mu\text{A}$                  | 1.2 | 1.7 | 2.2  |               |
| Zero gate voltage drain current  | $I_{\text{DSS}}$            | $V_{\text{DS}}=60\text{ V}$ , $V_{\text{GS}}=0\text{ V}$ ,<br>$T_j=25\text{ °C}$      | -   | 0.1 | 1    | $\mu\text{A}$ |
|                                  |                             | $V_{\text{DS}}=60\text{ V}$ , $V_{\text{GS}}=0\text{ V}$ ,<br>$T_j=125\text{ °C}$     | -   | 10  | 100  |               |
| Gate-source leakage current      | $I_{\text{GSS}}$            | $V_{\text{GS}}=20\text{ V}$ , $V_{\text{DS}}=0\text{ V}$                              | -   | 10  | 100  | nA            |
| Drain-source on-state resistance | $R_{\text{DS(on)}}$         | $V_{\text{GS}}=4.5\text{ V}$ , $I_{\text{D}}=25\text{ A}$                             | -   | 8.0 | 12.1 | m $\Omega$    |
|                                  |                             | $V_{\text{GS}}=10\text{ V}$ , $I_{\text{D}}=50\text{ A}$                              | -   | 5.4 | 6.7  |               |
| Gate resistance                  | $R_{\text{G}}$              |                                                                                       | -   | 1.3 | -    | $\Omega$      |
| Transconductance                 | $g_{\text{fs}}$             | $ V_{\text{DS}} >2 I_{\text{D}} R_{\text{DS(on)max}}$ ,<br>$I_{\text{D}}=50\text{ A}$ | 38  | 77  | -    | S             |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

### Dynamic characteristics

|                              |              |                                                                                     |   |      |      |    |
|------------------------------|--------------|-------------------------------------------------------------------------------------|---|------|------|----|
| Input capacitance            | $C_{iss}$    | $V_{GS}=0\text{ V}, V_{DS}=30\text{ V},$<br>$f=1\text{ MHz}$                        | - | 3800 | 5100 | pF |
| Output capacitance           | $C_{oss}$    |                                                                                     | - | 710  | 940  |    |
| Reverse transfer capacitance | $C_{rss}$    |                                                                                     | - | 32   | -    |    |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD}=30\text{ V}, V_{GS}=10\text{ V},$<br>$I_D=20\text{ A}, R_{G,ext}=2\ \Omega$ | - | 15   | -    | ns |
| Rise time                    | $t_r$        |                                                                                     | - | 26   | -    |    |
| Turn-off delay time          | $t_{d(off)}$ |                                                                                     | - | 37   | -    |    |
| Fall time                    | $t_f$        |                                                                                     | - | 7    | -    |    |

### Gate Charge Characteristics<sup>5)</sup>

|                          |               |                                                                             |   |     |    |    |
|--------------------------|---------------|-----------------------------------------------------------------------------|---|-----|----|----|
| Gate to source charge    | $Q_{gs}$      | $V_{DD}=30\text{ V}, I_D=50\text{ A},$<br>$V_{GS}=0\text{ to }4.5\text{ V}$ | - | 14  | -  | nC |
| Gate charge at threshold | $Q_{g(th)}$   |                                                                             | - | 7   | -  |    |
| Gate to drain charge     | $Q_{gd}$      |                                                                             | - | 5   | -  |    |
| Switching charge         | $Q_{sw}$      |                                                                             | - | 12  | -  |    |
| Gate charge total        | $Q_g$         |                                                                             | - | 23  | 30 |    |
| Gate plateau voltage     | $V_{plateau}$ |                                                                             | - | 3.6 | -  | V  |
| Gate charge total        | $Q_g$         | $V_{DD}=30\text{ V}, I_D=50\text{ A},$<br>$V_{GS}=0\text{ to }10\text{ V}$  | - | 51  | 67 | nC |
| Output charge            | $Q_{oss}$     | $V_{DD}=30\text{ V}, V_{GS}=0\text{ V}$                                     | - | 35  | 47 |    |

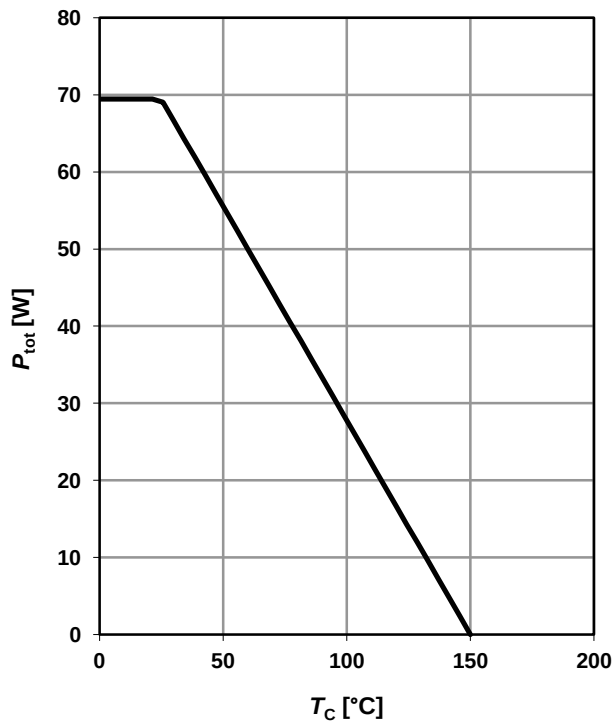
### Reverse Diode

|                                  |               |                                                                           |   |     |     |    |
|----------------------------------|---------------|---------------------------------------------------------------------------|---|-----|-----|----|
| Diode continuous forward current | $I_S$         | $T_C=25\text{ °C}$                                                        | - | -   | 50  | A  |
| Diode pulse current              | $I_{S,pulse}$ |                                                                           | - | -   | 200 |    |
| Diode forward voltage            | $V_{SD}$      | $V_{GS}=0\text{ V}, I_F=50\text{ A},$<br>$T_J=25\text{ °C}$               | - | 0.9 | 1.2 | V  |
| Reverse recovery time            | $t_{rr}$      | $V_R=30\text{ V}, I_F=20\text{ A},$<br>$di_F/dt=100\text{ A}/\mu\text{s}$ | - | 40  | -   | ns |
| Reverse recovery charge          | $Q_{rr}$      |                                                                           | - | 39  | -   | nC |

<sup>5)</sup> See figure 16 for gate charge parameter definition

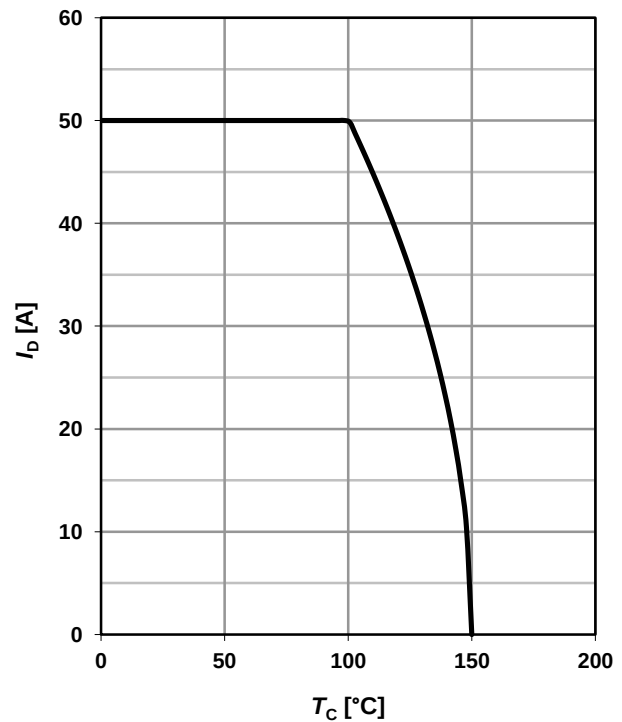
### 1 Power dissipation

$$P_{\text{tot}} = f(T_C)$$



### 2 Drain current

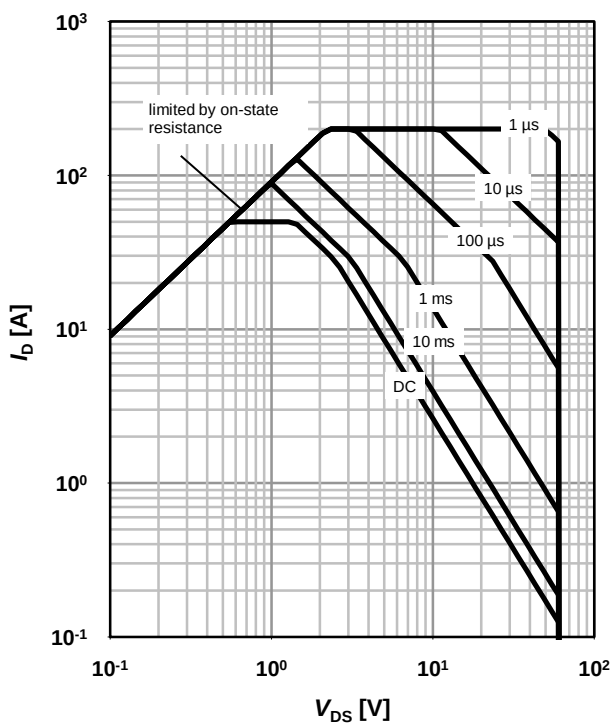
$$I_D = f(T_C); V_{GS} \geq 10 \text{ V}$$



### 3 Safe operating area

$$I_D = f(V_{DS}); T_C = 25 \text{ °C}; D = 0$$

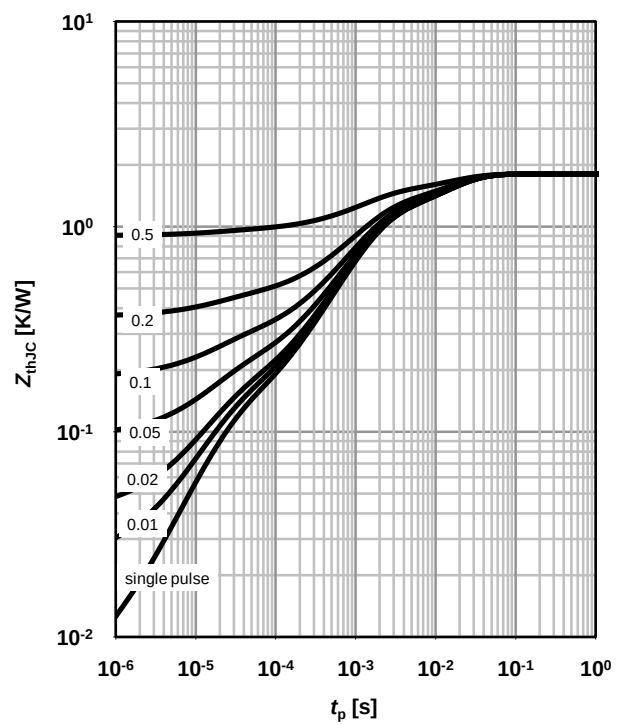
parameter:  $t_p$



### 4 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

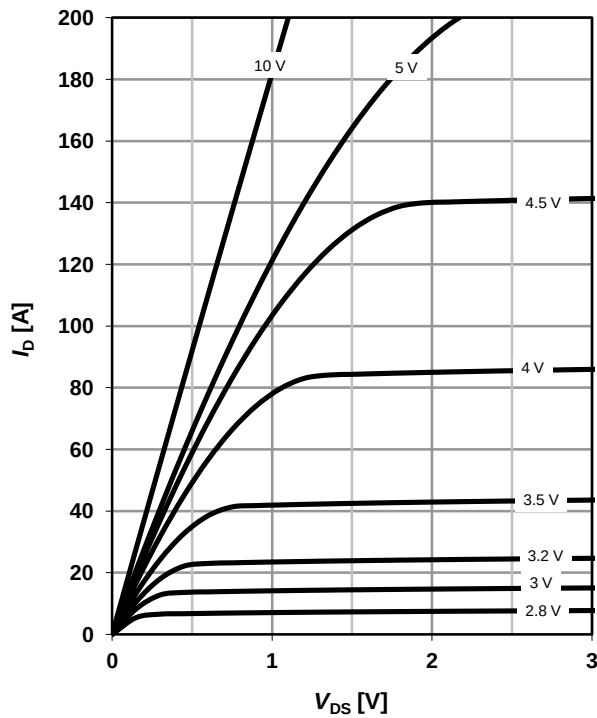
parameter:  $D = t_p/T$



### 5 Typ. output characteristics

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

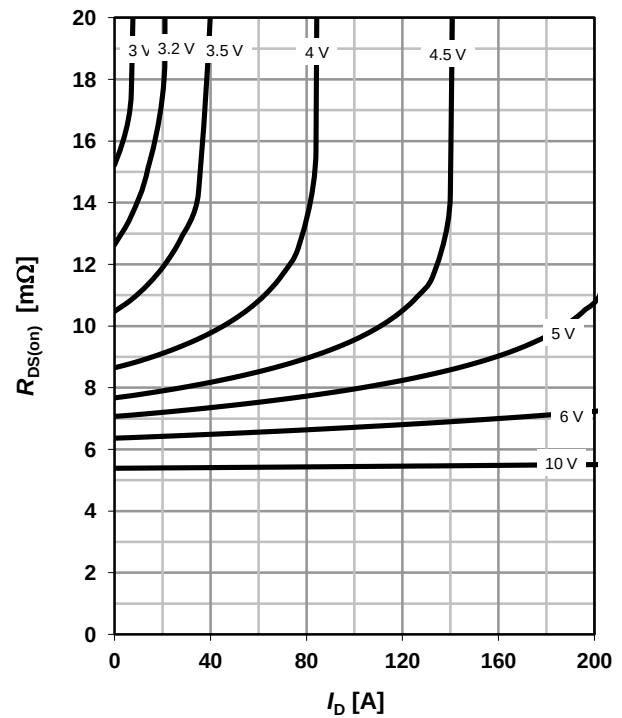
parameter:  $V_{GS}$



### 6 Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$$

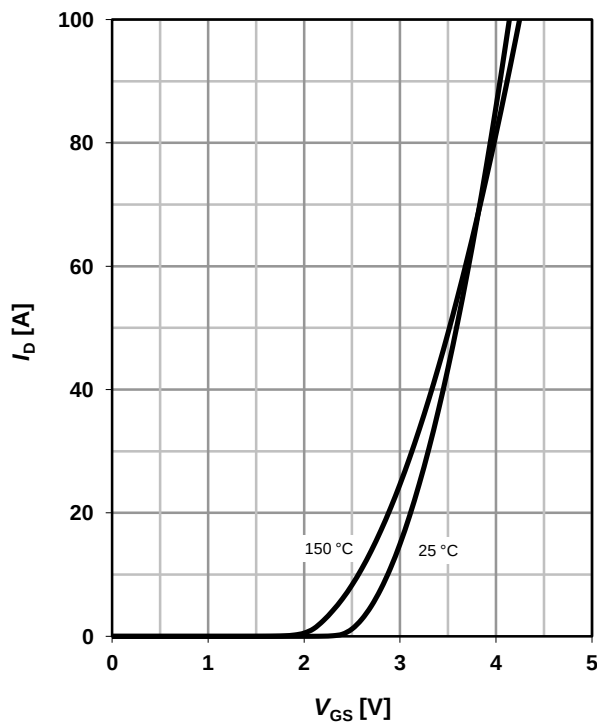
parameter:  $V_{GS}$



### 7 Typ. transfer characteristics

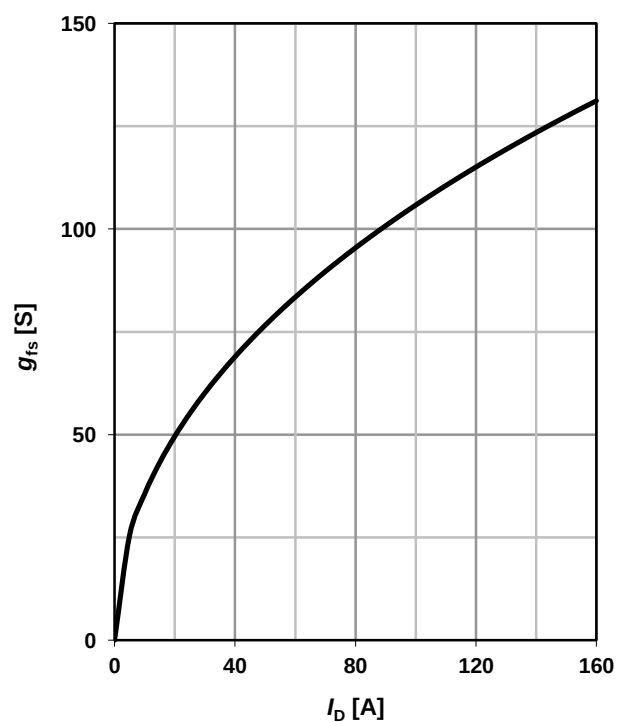
$$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$$

parameter:  $T_j$

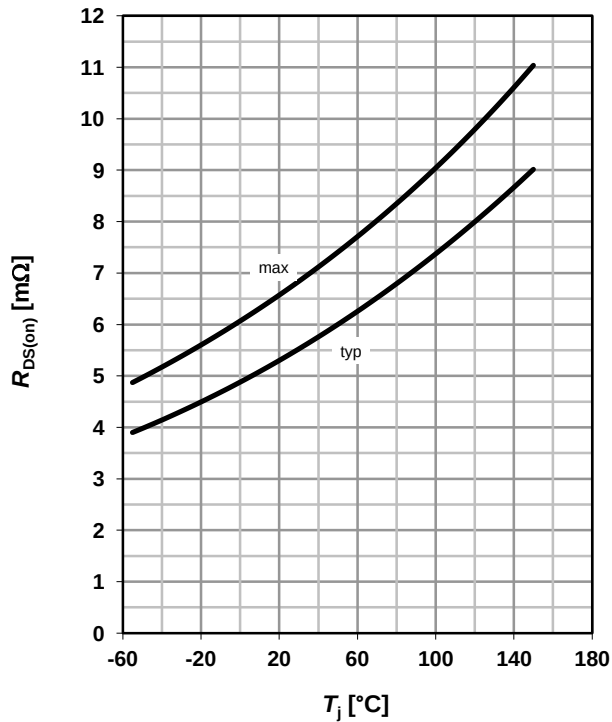


### 8 Typ. forward transconductance

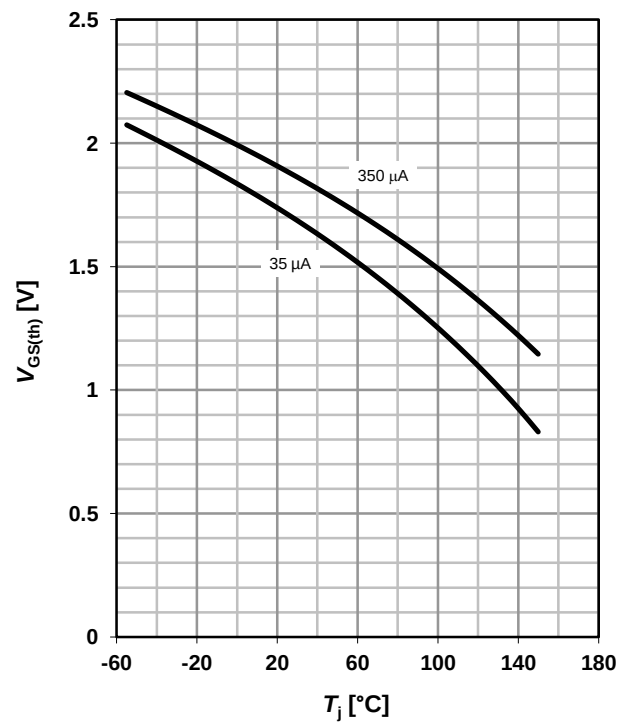
$$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$$



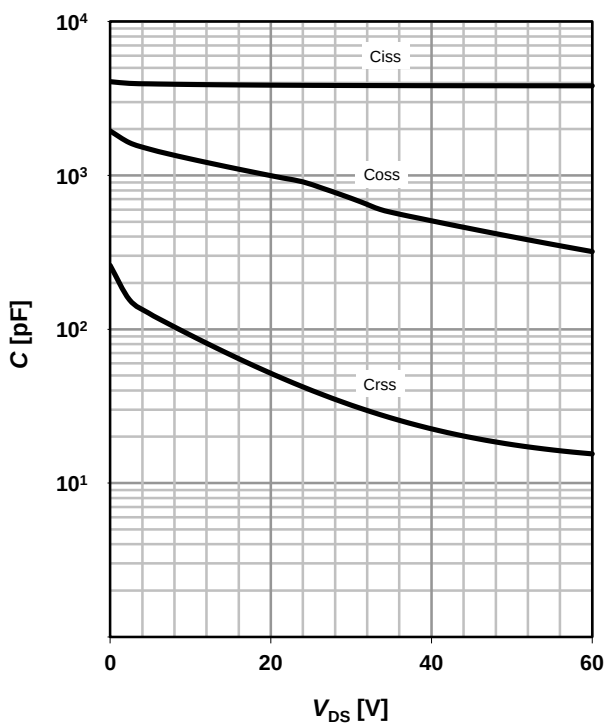
## 9 Drain-source on-state resistance

 $R_{DS(on)} = f(T_j); I_D = 50 \text{ A}; V_{GS} = 10 \text{ V}$ 


## 10 Typ. gate threshold voltage

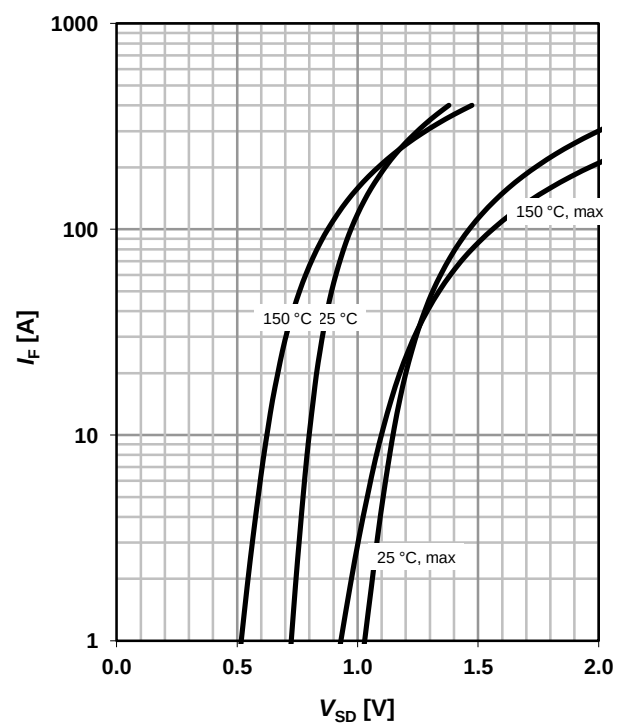
 $V_{GS(th)} = f(T_j); V_{GS} = V_{DS}; I_D = 100 \text{ μA}$ 


## 11 Typ. capacitances

 $C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$ 


## 12 Forward characteristics of reverse diode

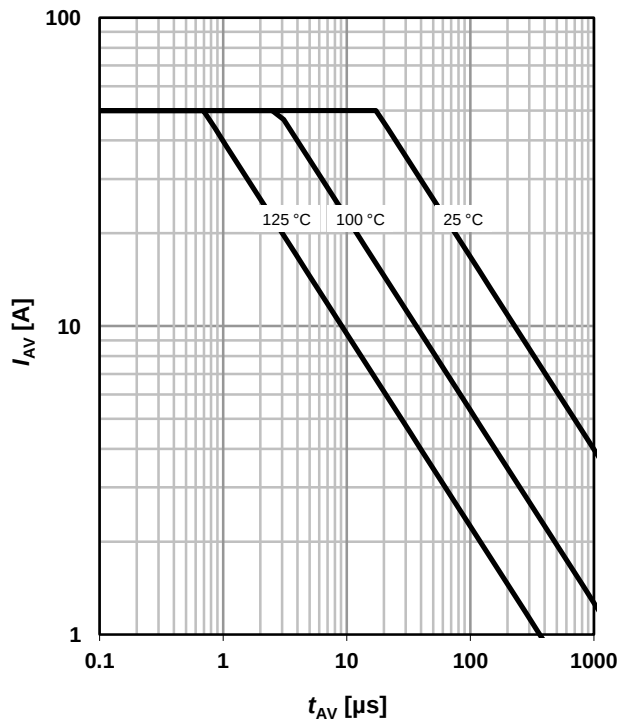
 $I_F = f(V_{SD})$ 

parameter:  $T_j$ 


### 13 Avalanche characteristics

$$I_{AS}=f(t_{AV}); R_{GS}=25\ \Omega$$

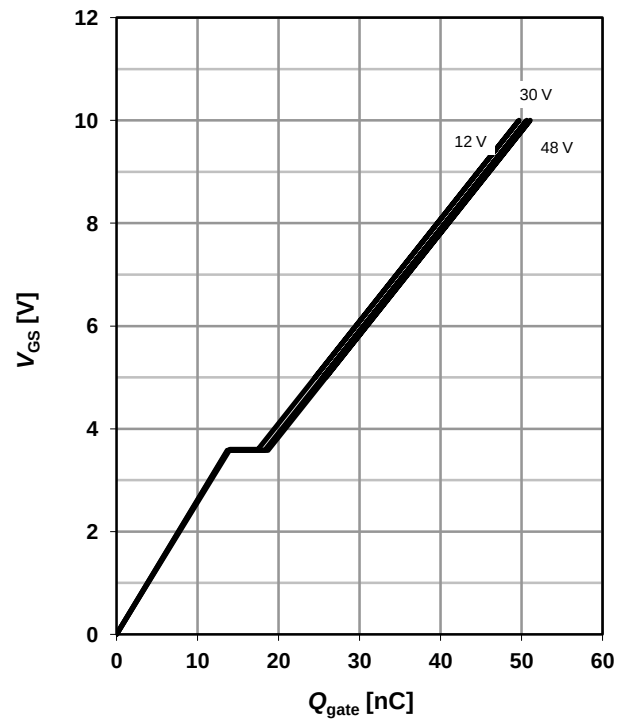
parameter:  $T_{j(\text{start})}$



### 14 Typ. gate charge

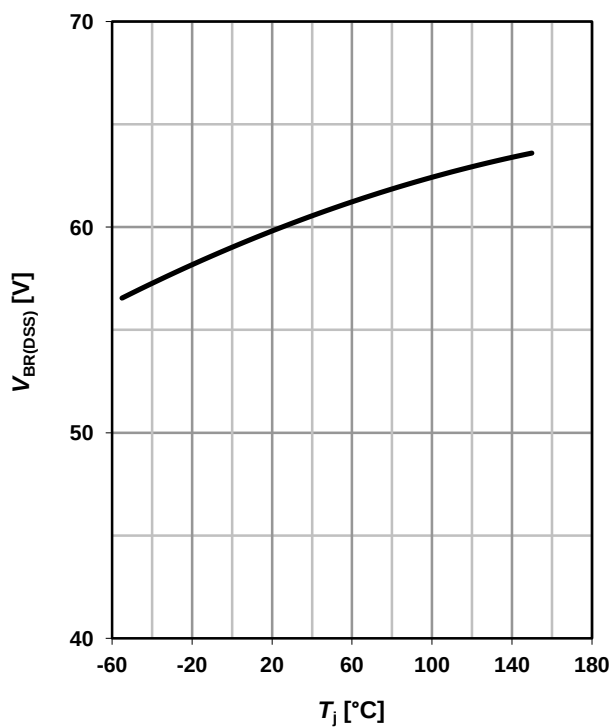
$$V_{GS}=f(Q_{\text{gate}}); I_D=50\ \text{A pulsed}$$

parameter:  $V_{DD}$

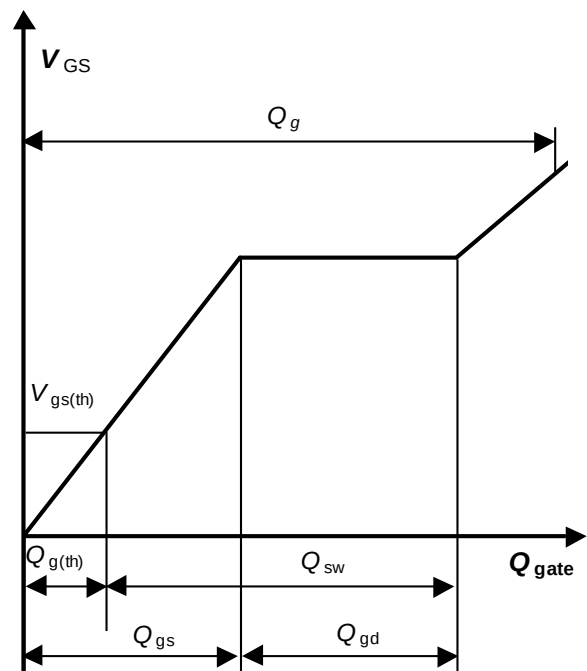


### 15 Drain-source breakdown voltage

$$V_{BR(DSS)}=f(T_j); I_D=1\ \text{mA}$$

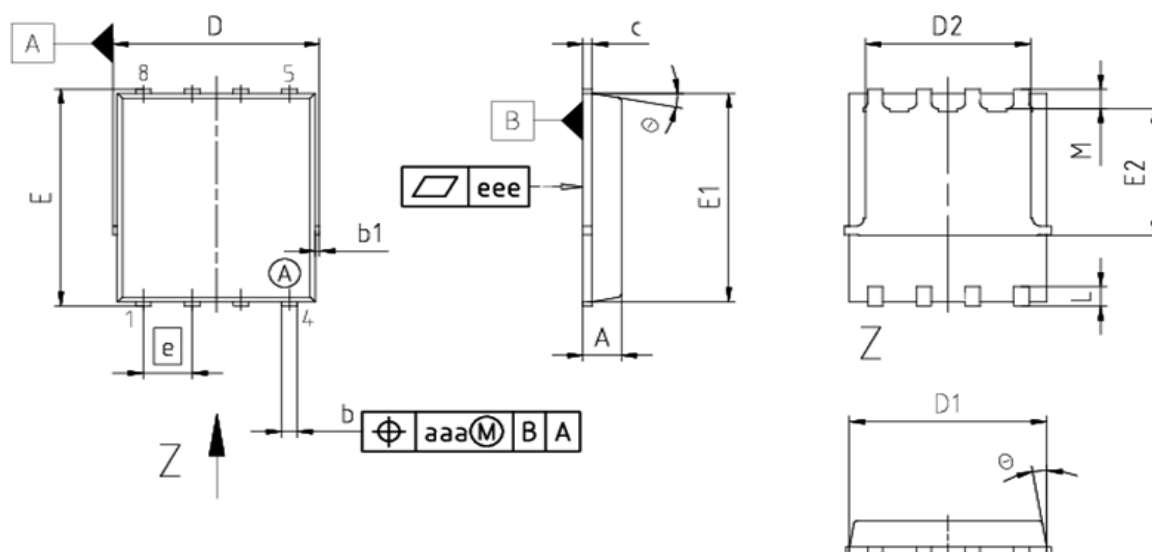


### 16 Gate charge waveforms

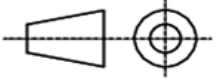


## Package Outline

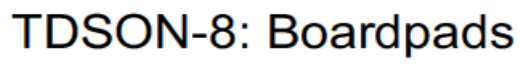
## PG-TDSON-8-5



| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.90        | 1.10 |
| b   | 0.31        | 0.54 |
| b1  | 0.02        | 0.22 |
| c   | 0.15        | 0.35 |
| D   | 5.15        | 5.49 |
| D1  | 4.95        | 5.35 |
| D2  | 3.70        | 4.40 |
| E   | 5.95        | 6.35 |
| E1  | 5.70        | 6.10 |
| E2  | 3.40        | 3.80 |
| e   | 1.27        |      |
| N   | 8           |      |
| L   | 0.45        | 0.71 |
| M   | 0.45        | 0.75 |
| G   | 8.5°        | 12°  |
| aaa | 0.25        |      |
| eee | 0.08        |      |

|                                                                                                             |  |
|-------------------------------------------------------------------------------------------------------------|--|
| DOCUMENT NO.<br>Z8B00003332                                                                                 |  |
| SCALE<br>0 2 4mm                                                                                            |  |
| EUROPEAN PROJECTION<br> |  |
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